

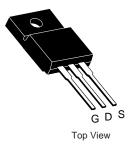
RoHS

COMPLIANT

P-Channel 60 V (D-S) MOSFET

PRODUCT	SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A)	Q _g (Typ.)
- 60	0.050 at V _{GS} = - 10 V	- 30	67
- 00	0.060 at V _{GS} = - 4.5 V	- 24	07

TO-220 FULLPAK



FEATURES

GO

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET ٠

s

P-Channel MOSFET

- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ABSOLUTE MAXIMUM RATINGS	$(T_C = 25 \ ^{\circ}C, \text{ unless oth})$	nerwise noted)			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current ($T_1 = 150 \text{ °C}$)	T _C = 25 °C	1-	- 30		
Continuous Drain Current $(1) = 150^{\circ}$ C)	T _C = 70 °C	I _D	- 29	A	
Pulsed Drain Current (t = 300 μs)		I _{DM}	- 100	A	
Avalanche Current		I _{AS}	- 32		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	51	mJ	
	T _C = 25 °C		41.7 ^b	14/	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	2.1	W	
Operating Junction and Storage Temperature Rat	nge	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/W
Junction-to-Case (Drain)	R _{thJC}	3	0,00

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).



SPECIFICATIONS ($T_J = 25$	°C, unless o	otherwise noted)				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static		· · · ·				
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_D = -250 \mu A$	- 60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 2.5	v
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA
		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	μA
		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 150 \text{ °C}$			- 250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 10 V, V_{GS} = - 10 V	- 30			А
	P	V _{GS} = - 10 V, I _D = - 14 A		0.050		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 12 A		0.060		52
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 14 A		40		S
Dynamic ^b						
Input Capacitance	C _{iss}			1765		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 20 V, f = 1 MHz		230		
Reverse Transfer Capacitance	C _{rss}			180		
Total Gate Charge ^c	Qg			67		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -14 \text{ A}$		13.5		nC
Gate-Drain Charge ^c	Q _{gd}			14		
Gate Resistance	Rg	f = 1 MHz	0.5	2.5	5	Ω
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	V_{DD} = - 20 V, R_L = 2 Ω		11	20	- ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		42	63	
Fall Time ^c	t _f			12	20	
Drain-Source Body Diode Ratings a	nd Characteri	stics T _C = 25 °C ^b				
Continuous Current	۱ _S				- 36	
Pulsed Current	I _{SM}				- 100	A
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V
Reverse Recovery Time	t _{rr}			38	57	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 10 A, dl/dt = 100 A/μs		2.3	3.5	А
Reverse Recovery Charge	Q _{rr}	1 1		40	60	nC

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

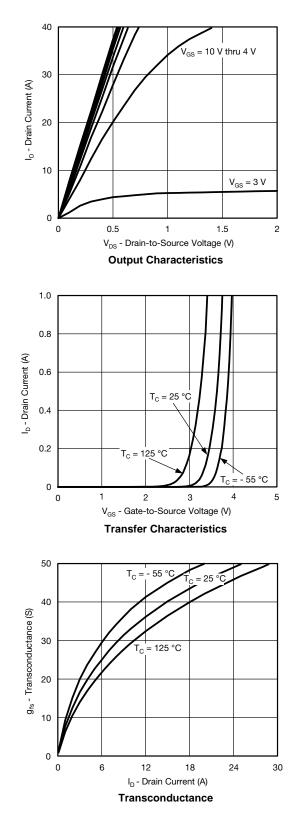
c. Independent of operating temperature.

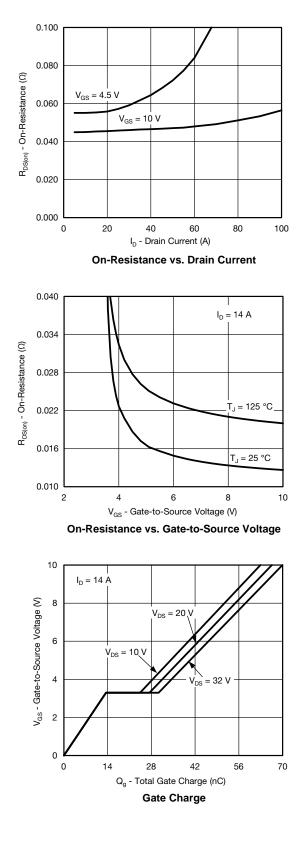
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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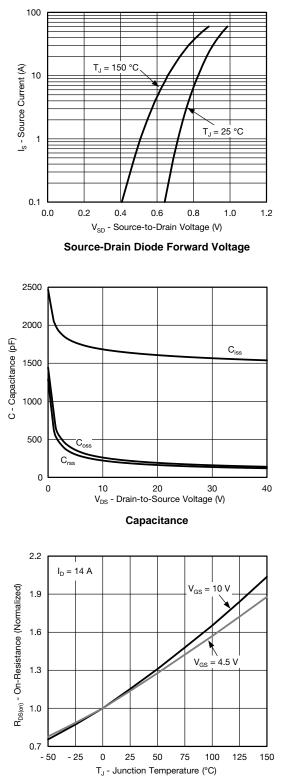
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



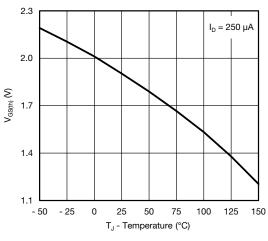




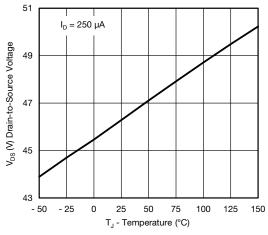
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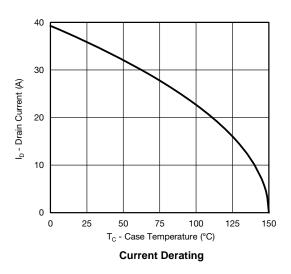
On-Resistance vs. Junction Temperature



Threshold Voltage

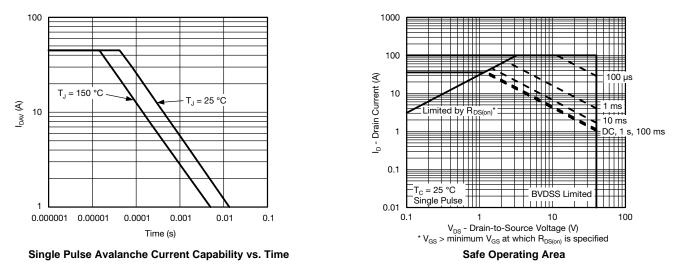


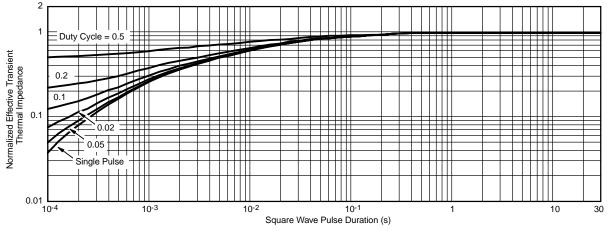
Drain Source Breakdown vs. Junction Temperature





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

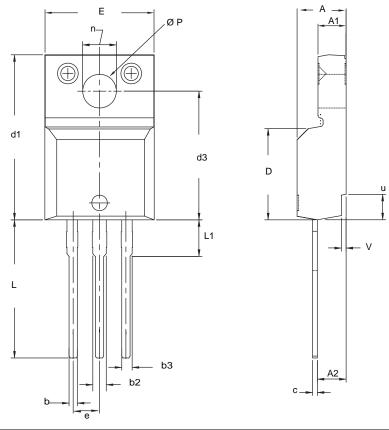




Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

Notes

1. To be used only for process drawing. 2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads. 3. All critical dimensions should C meet $C_{pk} > 1.33$. 4. All dimensions include burrs and plating thickness. 5. No chipping or package damage.



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